

In the Claims:

Please cancel claim 7.

Please amend claim 2 as set forth below in the "Listing of Claims":

LISTING OF CLAIMS

Claim 1 (Canceled)

Claim 2 (Currently Amended): An epoxy resin composition for encapsulation of semiconductors which comprises (A) a spherical alumina, (B) an ultrafine silica having a specific surface area of 120-280 m²/g, (C) a silicone compound, (D) an epoxy resin, (E) a phenolic resin curing agent, and (F) a curing accelerator, said ultrafine silica being contained in an amount of 0.2-0.8% by weight based on the total weight of the resin composition,

wherein said silicone compound (C) is a polyorganosiloxane and is present in an amount of from 0.3 to 2.0% by weight based on the total weight of the resin composition, and

wherein the spherical alumina is present in an amount of from 85% to 92% by weight based on the total weight of the resin composition.

Claim 3 (Canceled)

Claim 4 (Withdrawn): A semiconductor apparatus in which a semiconductor element is mounted on one side of a substrate and substantially only the one side of the substrate on which the semiconductor element is mounted is encapsulated with the epoxy resin composition for semiconductor encapsulation of claim 2.

Claim 5 (Canceled)

Claim 6 (Withdrawn): A method of encapsulating a semiconductor apparatus having a semiconductor element mounted on one side of a substrate, comprising encapsulating substantially only the one side of the substrate on which the semiconductor element is mounted with the epoxy resin composition of claim 2.

Claim 7 (Canceled)